

What is claimed is:

Sub 247.

An IC socket comprising:

a multitude of elastic contact pins arranged to form an array;

a socket body by which respective lower end sections of said contact pins are movably supported;

5 a floating member which is vertically movably held above said socket body and by which respective upper end sections of said contact pins are movably supported; and

a cover member constructed to be fitted to said floating member so as to press said floating member toward said socket body,

10 wherein said floating member is provided with: a multitude of guide means for regulating amount of projection of the upper end sections of said contact pins from said floating member; and a container section for containing an IC package to bring a multitude of terminals of the IC package into contact with the upper end sections

15 of said multitude of contact pins, respectively, and

wherein where said cover member is fitted to said floating member and pressed down upon the IC package being put in said container section, contact at predetermined pressure is obtained between the lower end sections of said contact pins and electrodes of

20 a printed circuit board and between the upper end sections of said contact pins and the terminals of the IC package, respectively.

2. An IC socket comprising:

a multitude of elastic contact pins arranged to form an array;

a socket body by which respective lower end sections of said contact pins are fixedly supported as projecting downward therefrom;

5 a floating member which is vertically movably held above said socket body and by which respective upper end sections of said contact pins are movably supported; and

a cover member constructed to be fitted to said floating member so as to press said floating member toward said socket body,

10 wherein said floating member is provided with: a multitude of guide means for regulating amount of projection of the upper end sections of said contact pins from said floating member; and a container section for containing an IC package to bring a multitude of terminals of the IC package into contact with the upper end sections
15 of said multitude of contact pins, respectively, and

wherein where said cover member is fitted to said floating member and pressed down upon the IC package being put in said container section, contact at predetermined pressure is obtained between the upper end sections of said contact pins and the terminals
20 of the IC package.

3. An IC socket according to claim 2, wherein the terminals of the IC package are constructed to be ball terminals and an inclined face is formed at a tip of the upper end section of each contact pin so as to be contacted with and rubbed against a portion, exclusive of
5 a bottom point, of each ball terminal.

Sub 57. An IC socket according to claims 1 or 2, wherein said

5 container section forms an aperture in said floating member, and said
cover member has a first surface to be contacted with a top surface of
said floating member and a second surface to be contacted with an
upper surface of the IC package which is contained in said container
section, said IC socket being constructed such that said second
surface is brought into contact with the upper surface of the IC
package contained in said container section before said first surface
is brought into contact with said top surface of said floating member
10 in a process of said cover member being fitted in place.

5 5. An IC socket according to claims 1 or 2, wherein the terminals
of the IC package are constructed to be solder balls, and said guide
means of said floating member are arranged such that the upper end
sections of said contact pins are directed toward respective centers
of the solder balls.

6. An IC socket according to claims 1 or 2, wherein the tip of
the upper end section of each contact pin has at least one face which
is inclined in reference to a longitudinal direction of said contact
pin.

5 7. An IC socket according to claims 1 or 2, wherein each of said
contact pins has an arc-shaped middle section between the upper end
section and the lower end section, said contact pin being cornered at
points where the upper end section and the lower end section meet the
middle section, respectively, such that the upper end section and the

~~lower end section are aligned.~~

~~Sub 6~~ An IC socket according to claims 1 or 2, wherein each of said contact pins has a step portion which is formed at a position lower than the tip of the upper end section of said contact pin by a predetermined distance.

9. An IC socket according to claims 1 or 2, wherein each of said guide means of said floating member forms a guide hole which is slightly tapered from a lower border to an upper border thereof.

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~~10.~~ An IC socket according to claim ~~8~~⁶, wherein the lower border of said guide hole has a curved face.